

TARGET IMPLEMENTATION DATE: 1-MAY-2013

Product Change Notice

PCN Number: 13-0313-02A Issue Date: 05-06-2013

Exar Corporation

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PRODUCTS AFFECTED:	SP3080EEN-L/TR, SP3080EEN-L, SP3081EEN-L/TR, SP3081EEN-L, SP3082EEN-L/TR, SP3082EEN-L/TR, SP3083EEN-L/TR, SP3084EEN-L, SP3084EEN-L, SP3084EEN-L, SP3085EEN-L/TR, SP3085EEN-L/TR, SP3086EEN-L/TR, SP3087EEN-L/TR, SP3088EEN-L/TR, SP3088EEN-L	
CHANGE CATEGORY:		
	Na sacs	□ Dagkaga
Material		Package
Design	□ Datasheet	Packing/Shipping
Other (specify)		
DESCRIPTION OF CHANGE:		
Qualified TSMC as an alternate foundry supplier.		
Qualified Cu wire bonding assembly process at Carsem, Ipoh, Malaysia and ASE, Chung-Li, Taiwan.		
IMPACT OF CHANGE:		
Expect no change to form, fit or function of the part as a result of this die technology upgrade and specification		
improvement.		

Please contact customer support (customersupport@exar.com) for sample date availability or qualification data

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